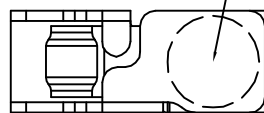


02 09/07-'15

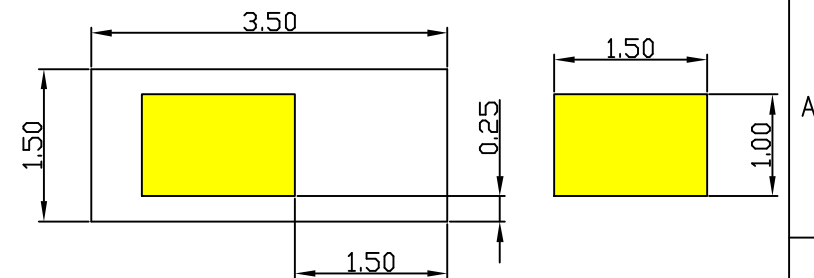
A



Place Area NOZZLE



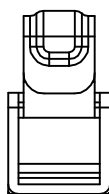
B



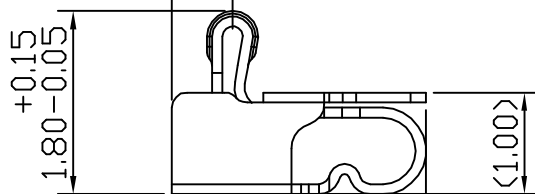
RECOMMENDED SOLDERING PCB LAYOUT

TOLERANCE(.XX±0.05)

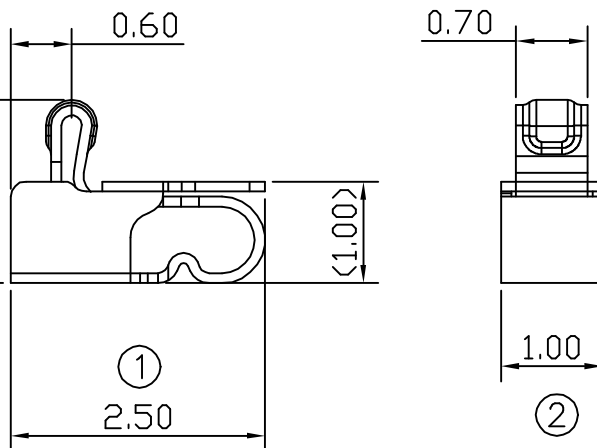
C



③



D

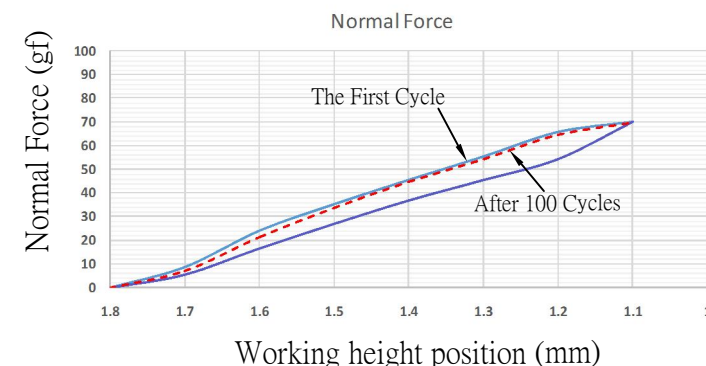
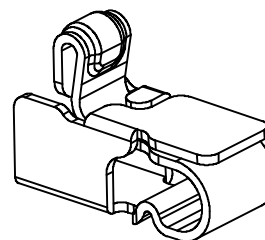


E

Note:

1. Material: Titanium copper Thickness 0.10mm
2. Electroplate:
 - Gold Flash on contact area
 - Gold Flash on solder area
 - Nickel underplating over all
3. Electrical Characteristics:
 - 3-1 Current Voltage: 12V
 - 3-2 Current Rate: 3A
 - 3-3 Contact Resistance: Normal Compression<30mΩ
4. Working Height of Application: 1.10~1.40 mm
5. Spring Force Tolerance is ±20gf
6. Operating Temperature: -20℃~+85℃

F



01	09/07-'15	DESIGN_IMPROVEMENT
00	12/12-'13	Design creation
REV	Date	Description
DRAFT	Duke Chen	12/12-'13
CHECKER	Gabby Weng	12/12-'13
APPROVAL	Jacky Lin	12/12-'13
SHEET	1-2	SCALE
UNIT	mm	Not to scale

RoHS
Compatible

TOLERANCE/CLASS			
RANGE(mm)	1	2	3
≤30	±0.10	0.15	0.20
30<~≤120	±0.15	0.20	0.30
120<~≤300	±0.20	0.30	0.50
300<	±0.30	0.50	0.80
ANGLES	±2.5°		



EMI STOP CORP.

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QTT-18G

CUS P/N